

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Notes 3 & 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

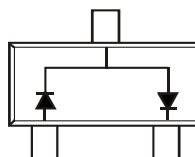
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe
(Lead Free Plating). Solderable per MIL-STD-202, Method 208 
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)

SOT23



Top View

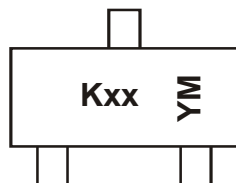

 Top View
Internal Schematic

Ordering Information (Note 5)

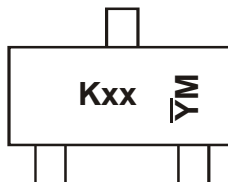
Part Number	Compliance	Case	Packaging
BAV99-7-F	Standard	SOT23	3,000/Tape & Reel
BAV99-13-F	Standard	SOT23	10,000/Tape & Reel
BAV99Q-7-F	Automotive	SOT23	3,000/Tape & Reel
BAV99Q-13-F	Automotive	SOT23	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Product manufactured with Date Code 9W (week 39, 2009) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 9W are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



xx = JE, Product Type Marking Code
 YM = Date Code Marking for Shanghai
 Assembly / Test site
 Y = Year (ex: A = 2013)
 M = Month (ex: 9 = September)



xx = JE, Product Type Marking Code
 YM = Date Code Marking for Chengdu
 Assembly / Test site
 Y = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999		2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	J	K		T	U	V	W	X	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	75	V
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current (Note 6)	I _{FM}	300	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0s	I _{FSM}	2.0 1.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	75	—	V	I _R = 2.5μA
Forward Voltage	V _F	—	0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 7)	I _R	—	2.5 50 30 25	μA μA μA nA	V _R = 75V V _R = 75V, T _J = +150°C V _R = 25V, T _J = +150°C V _R = 20V
Total Capacitance	C _T	—	2.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

Notes: 6. Part mounted on Polyimide PC board with pad dimensions 1.13mm x 1.27mm.
7. Short duration pulse test used to minimize self-heating effect.

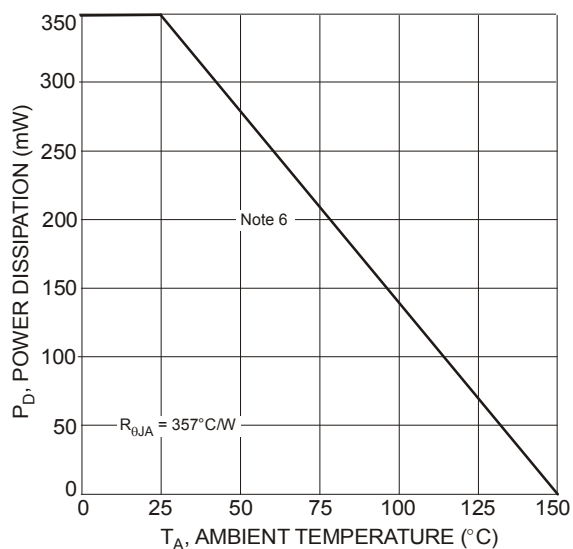


Fig. 1 Power Derating Curve

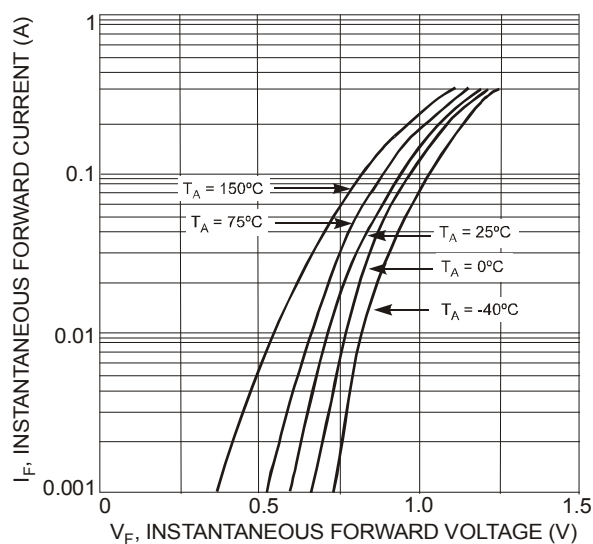


Fig. 2 Forward Characteristics

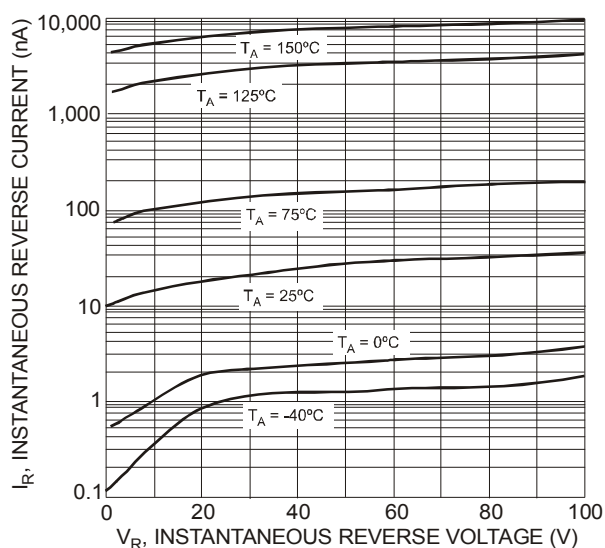


Fig. 3 Typical Reverse Characteristics

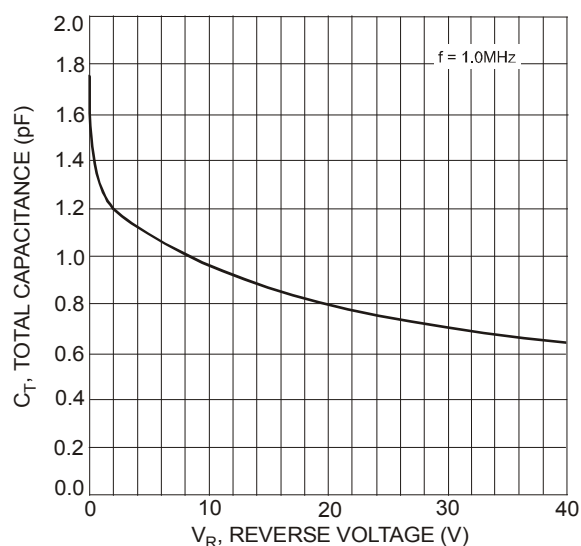
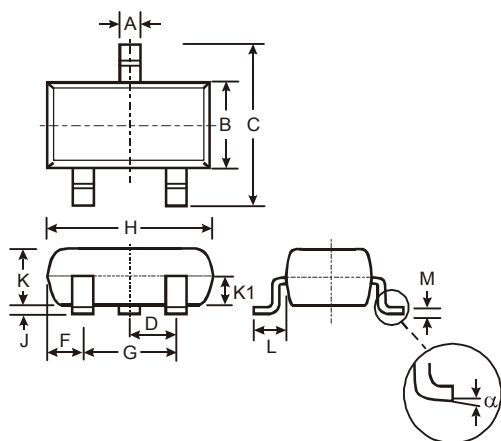


Fig. 4 Typical Capacitance vs. Reverse Voltage

Package Outline Dimensions

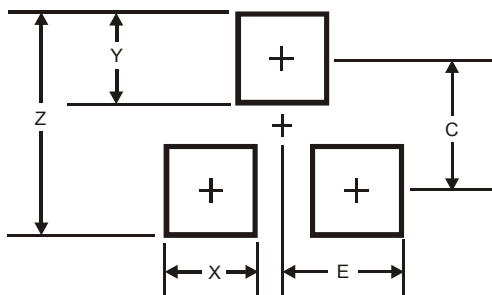
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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